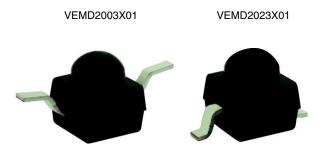


Vishay Semiconductors

Silicon PIN Photodiode



DESCRIPTION

VEMD2003X01 and VEMD2023X01 are high speed and high sensitive PIN photodiodes in a miniature surface mount package (SMD) with dome lens and daylight blocking filter. Filter is matched with IR emitters operating at wavelength of 830 nm to 950 nm. The photo sensitive area of the chip is 0.23 mm².

FEATURES

- · Package type: surface mount
- Package form: GW, RGW
- Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.55
- AEC-Q101 qualified
- High radiant sensitivity
- Daylight blocking filter matched with 830 nm to 950 nm IR emitters
- Fast response times
- Angle of half sensitivity: $\phi = \pm 35^{\circ}$
- Package matched with IR emitter series VSMB2943X01
- Floor life: 4 weeks, MSL 2a, acc. J-STD-020
- · Lead (Pb)-free reflow soldering
- Material categorization: For definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- High speed photo detector
- Infrared remote control
- Infrared data transmission
- Photo interrupters
- IR touch panels

PRODUCT SUMMARY				
COMPONENT	I _{ra} (μA) φ (deg)		λ _{0.5} (nm)	
VEMD2003X01	10	± 35	750 to 1050	
VEMD2023X01	10	± 35	750 to 1050	

Note

Test conditions see table "Basic Characteristics"

ORDERING INFORMATION				
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM	
VEMD2003X01	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Reverse gullwing	
VEMD2023X01	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Gullwing	

Note

• MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)					
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT	
Reverse voltage		V _R	60	V	
Power dissipation	$T_{amb} \le 25 \ ^{\circ}C$	Pv	215	mW	
Junction temperature		Тj	100	°C	
Operating temperature range		T _{amb}	- 40 to + 100	°C	
Storage temperature range		T _{stg}	- 40 to + 100	°C	
Soldering temperature	Acc. reflow solder profile fig. 7	T _{sd}	260	°C	
Thermal resistance junction/ambient	Acc. J-STD-051	R _{thJA}	250	K/W	





COMPLIANT

HALOGEN FREE <u>GREEN</u> (5-2008)



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BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I _F = 50 mA	V _F		1		V
Breakdown voltage	I _R = 100 μA, E = 0	V _(BR)	32			V
Reverse dark current	V _R = 10 V, E = 0	I _{ro}		1	10	nA
Diode capacitance	$V_{R} = 0 V, f = 1 MHz, E = 0$	CD		4		pF
	V _R = 5 V, f = 1 MHz, E = 0	CD		1.3		pF
Open circuit voltage	$E_e = 1 \text{ mW/cm}^2$, $\lambda = 950 \text{ nm}$	Vo		350		mV
Temperature coefficient of V_o	$E_e = 1 \text{ mW/cm}^2$, $\lambda = 950 \text{ nm}$	TK _{Vo}		- 2.6		mV/K
Short circuit current	$E_e = 1 \text{ mW/cm}^2$, $\lambda = 950 \text{ nm}$	l _k		10		μA
Temperature coefficient of I_k	$E_e = 1 \text{ mW/cm}^2$, $\lambda = 950 \text{ nm}$	TK _{lk}		0.1		%/K
Reverse light current	$E_e = 1 \text{ mW/cm}^2$, $\lambda = 950 \text{ nm}$, $V_R = 5 \text{ V}$	I _{ra}	7	10	14	μA
Angle of half sensitivity		φ		± 35		deg
Wavelength of peak sensitivity		λ _p		940		nm
Range of spectral bandwidth		λ _{0.5}		750 to 1050		nm
Rise time	$V_R = 10 \text{ V}, \text{R}_L = 1 \text{k}\Omega, \lambda = 820 \text{nm}$	t _r		100		ns
Fall time	$V_R = 10 \text{ V}, R_L = 1 \text{ k}\Omega, \lambda = 820 \text{ nm}$	t _f		100		ns

BASIC CHARACTERISTICS (Tamb = 25 °C, unless otherwise specified)

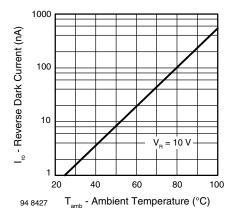


Fig. 1 - Reverse Dark Current vs. Ambient Temperature

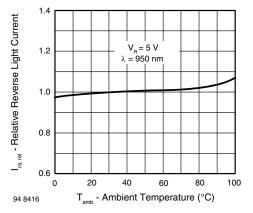


Fig. 2 - Relative Reverse Light Current vs. Ambient Temperature

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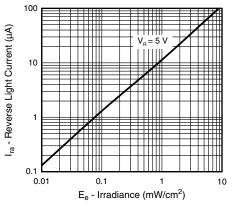


Fig. 3 - Reverse Light Current vs. Irradiance

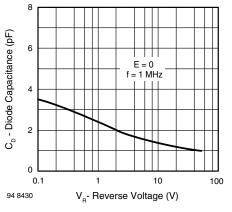
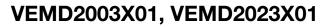


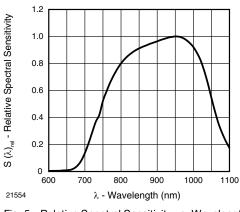
Fig. 4 - Diode Capacitance vs. Reverse Voltage

2 For technical questions, contact: <u>detectortechsupport@vishay.com</u> Document Number: 84147

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Fig. 5 - Relative Spectral Sensitivity vs. Wavelength

REFLOW SOLDER PROFILE

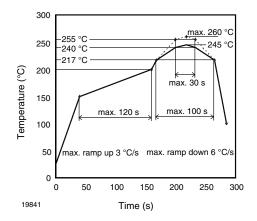


Fig. 7 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020D

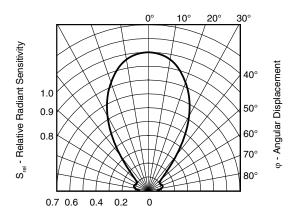


Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label: Floor life: 4 weeks Conditions: $T_{amb} < 30$ °C, RH < 60 % Moisture sensitivity level 2a, acc. to J-STD-020.

DRYING

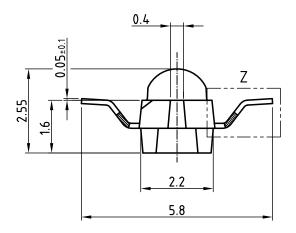
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.

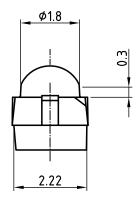
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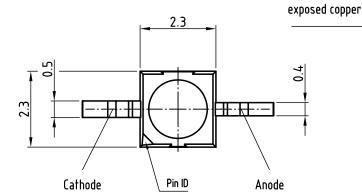
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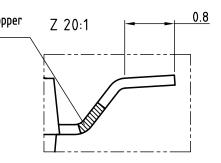


PACKAGE DIMENSIONS in millimeters: VEMD2003





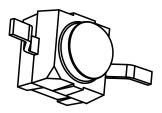


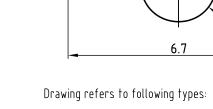




technical drawings according to DIN specifications

Dimensions in mm Not indicated tolerances ±0.2





Drawing-No.: 6.544-5409.01-4

Issue: prel. 03.08.12

1.7

0.75

VSMB2943RGX01 VSMF2893RGX01 VEMD2x23X01

Solder pad proposal

acc. IPC 7351

Ø2.3±0.1

Rev. 1.0, 04-Apr-13

4

Document Number: 84147

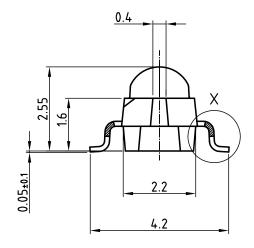
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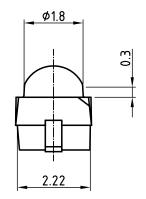
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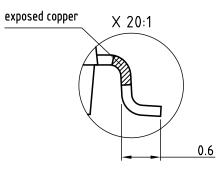
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PACKAGE DIMENSIONS in millimeters: VEMD2023

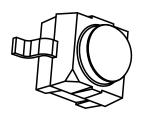


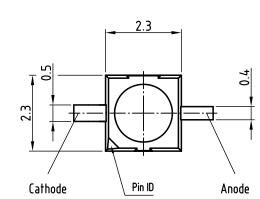


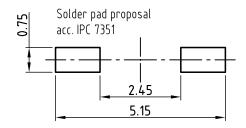




Dimensions in mm Not indicated tolerances ±0.2







Drawing refers to following types:

Drawing-No.: 6.544-5408.01-4 Issue: prel; 03.08.12 VSMB2943GX01 VSMF2893GX01 VEMD2x23X01

Rev. 1.0, 04-Apr-13

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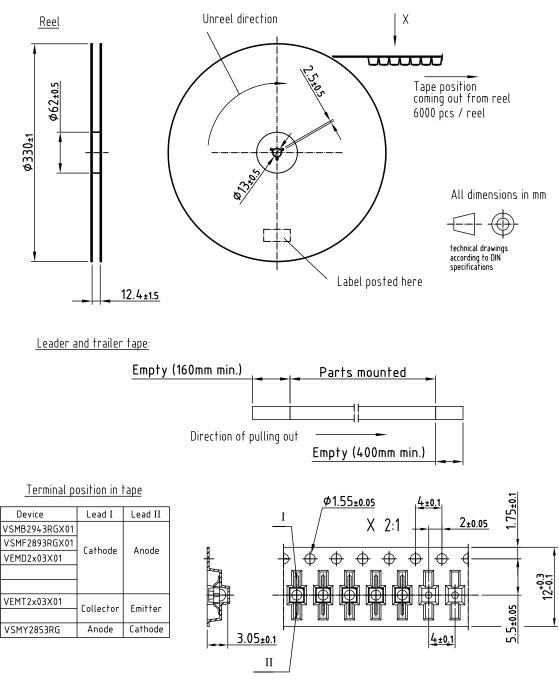
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TAPING AND REEL DIMENSIONS in millimeters: VEMD2003

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SHA



Drawing refers to following types: Reel dimensions and tape

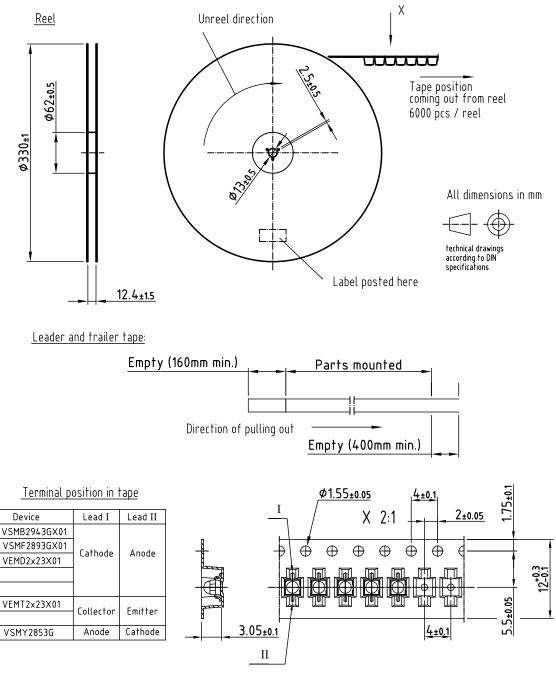
Drawing-No.: 9.800-5100.02-4 Issue: prel; 03.08.12

see table



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TAPING AND REEL DIMENSIONS in millimeters: VEMD2023



Drawing refers to following types: see table Reel dimensions and tape Drawing-No.: 9.800-5091.21-4 Issue: prel; 03.08.12

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